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United States Patent [19]
Kim

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[54] **METHOD AND APPARATUS FOR UNIFORMLY SPIN-COATING A PHOTORESIST MATERIAL**

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[57] **ABSTRACT**

[21] Appl. No.: **885,793**

A method and apparatus for uniformly spin-coating photoresist material on wafers before the wafers are subjected to a photoetching process. The spin-coating apparatus comprises a first rotating device for rotating a rotating connector about a first axis and a second rotating device located on the outer portion of the rotating connector. The second rotating device rotates a wafer about a second axis while the rotating connector rotates around the first axis. The first and second axes are parallel to each other but are spaced apart by a designated distance. The designated distance can be adjusted and a plurality of second rotating devices may be connected to outer portions of the rotating connector.

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[30] **Foreign Application Priority Data**

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[52] U.S. Cl. **427/240**; 427/385.5; 437/231; 118/52

[58] Field of Search 427/240, 385.5; 437/231; 118/52, 53

[56] **References Cited**

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20 Claims, 4 Drawing Sheets

